

Revision 20231109

## LNPTM THERMOCOMPTM COMPOUND 2C004

FP-EC-1004

## **DESCRIPTION**

Industrial

LNP THERMOCOMP 2C004 compound is based on Ethylene Tetrafluoroethylene (ETFE) resin containing 20% carbon fiber. Added features of this grade include: Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength
Fillers	Carbon Fiber
Polymer Types	Ethylene Tetrafluoroethylene Copolymer (ETFE)
Processing Techniques	Injection Molding
INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Energy Management, Electronic Components

Material Handling

## TYPICAL PROPERTY VALUES

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, break	60	MPa	ASTM D638
Tensile Strain, break	2.5	%	ASTM D638
Tensile Modulus, 50 mm/min	13300	MPa	ASTM D638
Flexural Stress	106	MPa	ASTM D790
Flexural Modulus	10540	MPa	ASTM D790
Tensile Stress, break	59	MPa	ISO 527
Tensile Strain, break	2	%	ISO 527
Tensile Modulus, 1 mm/min	12180	MPa	ISO 527
Flexural Stress	120	MPa	ISO 178
Flexural Modulus	10550	MPa	ISO 178
IMPACT (1)			
Izod Impact, unnotched, 23°C	587	J/m	ASTM D4812
Izod Impact, notched, 23°C	181	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	14	J	ASTM D3763
Multiaxial Impact	6	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	36	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	15	kJ/m²	ISO 180/1A
THERMAL (1)			
HDT, 0.45 MPa, 3.2 mm, unannealed	252	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	208	°C	ASTM D648
CTE, -40°C to 40°C, flow	2.52E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	5.4E-05	1/°C	ASTM E831



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
ATT 4000 . 4000 //	2.505.05	4.10.0	150 44250 2
CTE, -40°C to 40°C, flow	2.56E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	5.4E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	246	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	187	°C	ISO 75/Af
PHYSICAL (1)			
Density	1.75	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.09	%	ASTM D570
Mold Shrinkage, flow, 24 hrs <sup>(2)</sup>	0.7	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs <sup>(2)</sup>	2.2	%	ASTM D955
Mold Shrinkage, flow, 24 hrs <sup>(2)</sup>	0.65	%	ISO 294
Mold Shrinkage, xflow, 24 hrs <sup>(2)</sup>	2.22	%	ISO 294
Density	1.74	g/cm³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.12	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Melt Temperature	315	°C	
Front - Zone 3 Temperature	330 – 345	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	280 – 295	°C	
Mold Temperature	95 – 120	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.